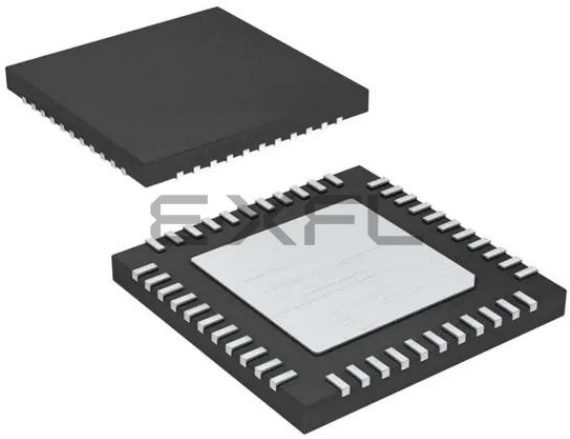

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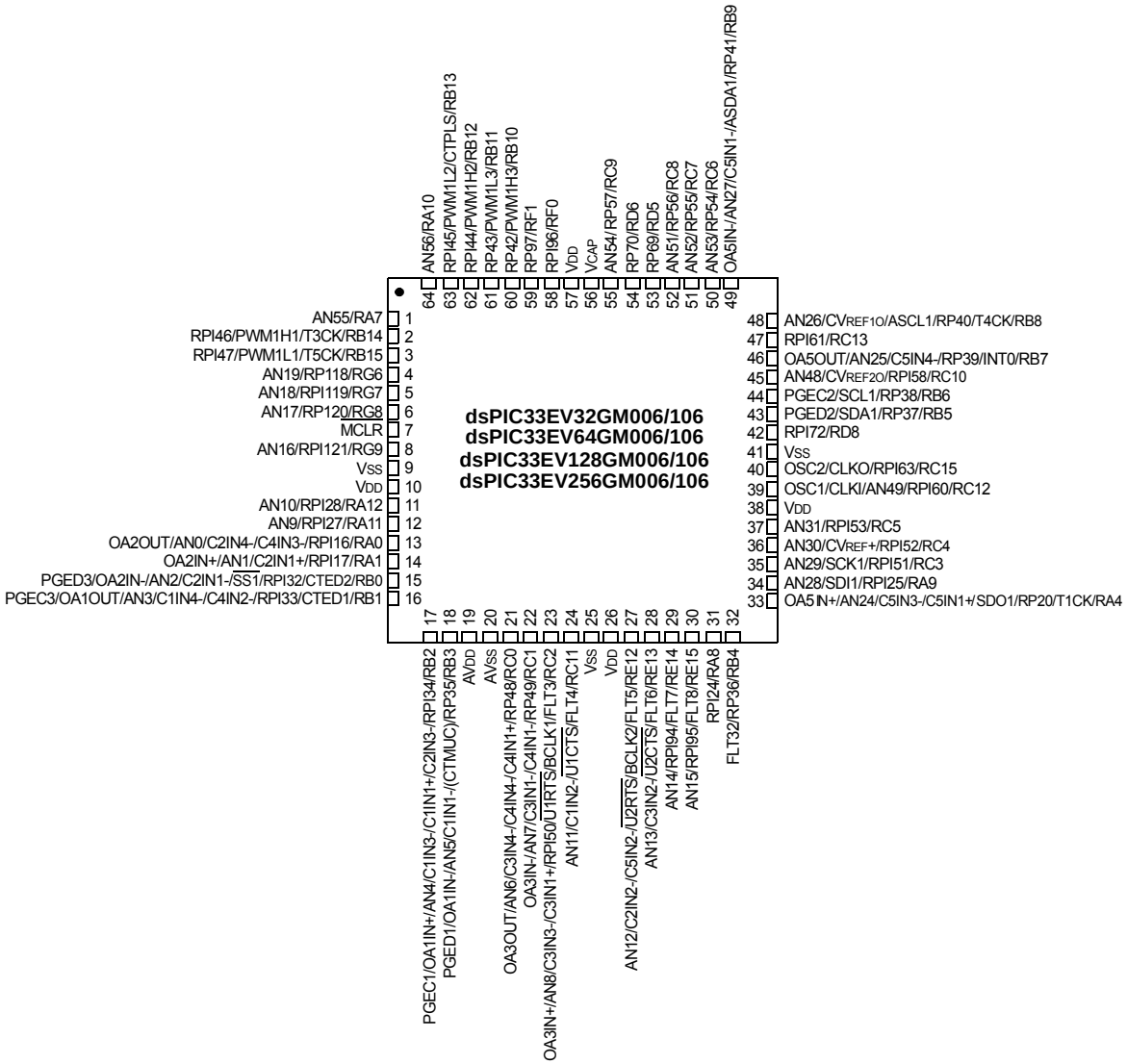
Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev256gm004-e-ml

Pin Diagrams (Continued)

64-Pin QFN(1,2,3,4)



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.5 "Peripheral Pin Select (PPS)"** for available peripherals and information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: If the op amp is selected when OPAEN (CMxCON<10>) = 1, the OAx input is used; otherwise, the ANx input is used.

4: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

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3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"CPU"** (DS70359) in the *"dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for digital signal processing. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space.

An instruction prefetch mechanism helps maintain throughput and provides predictable execution. Most instructions execute in a single-cycle effective execution rate, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction, PSV accesses and the table instructions. Overhead-free program loop constructs are supported using the `DO` and `REPEAT` instructions, both of which are interruptible at any point.

3.1 Registers

The dsPIC33EVXXXGM00X/10X family devices have sixteen, 16-bit Working registers in the programmer's model. Each of the Working registers can act as a Data, Address or Address Offset register. The sixteenth Working register (W15) operates as a Software Stack Pointer for interrupts and calls.

In addition, the dsPIC33EVXXXGM00X/10X devices include two alternate Working register sets, which consist of W0 through W14. The alternate registers can be made persistent to help reduce the saving and restoring of register content during Interrupt Service Routines (ISRs). The alternate Working registers can be assigned to a specific Interrupt Priority Level (IPL1 through IPL6) by configuring the CTXTx<2:0> bits in the FALTREG Configuration register.

The alternate Working registers can also be accessed manually by using the `CTXTSWP` instruction.

The CCTXI<2:0> and MCTXI<2:0> bits in the CTXTSTAT register can be used to identify the current, and most recent, manually selected Working register sets.

3.2 Instruction Set

The device instruction set has two classes of instructions: the MCU class of instructions and the DSP class of instructions. These two instruction classes are seamlessly integrated into the architecture and execute from a single execution unit. The instruction set includes many addressing modes and was designed for optimum C compiler efficiency.

3.3 Data Space Addressing

The Base Data Space can be addressed as 4K words or 8 Kbytes and is split into two blocks, referred to as X and Y data memory. Each memory block has its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear Data Space. On dsPIC33EV devices, certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y Data Space boundary is device-specific.

The upper 32 Kbytes of the Data Space (DS) memory map can optionally be mapped into Program Space (PS) at any 16K program word boundary. The Program-to-Data Space mapping feature, known as Program Space Visibility (PSV), lets any instruction access Program Space as if it were Data Space. Moreover, the Base Data Space address is used in conjunction with a Data Space Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space (EDS) address. The EDS can be addressed as 8M words or 16 Mbytes. For more information on EDS, PSV and table accesses, refer to **"Data Memory"** (DS70595) and **"dsPIC33E/PIC24E Program Memory"** (DS70000613) in the *"dsPIC33/PIC24 Family Reference Manual"*.

On dsPIC33EV devices, overhead-free circular buffers (Modulo Addressing) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. The X AGU Circular Addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data reordering for radix-2 FFT algorithms. Figure 3-1 illustrates the block diagram of the dsPIC33EVXXXGM00X/10X family devices.

3.4 Addressing Modes

The CPU supports these addressing modes:

- Inherent (no operand)
- Relative
- Literal
- Memory Direct
- Register Direct
- Register Indirect

Each instruction is associated with a predefined addressing mode group, depending upon its functional requirements. As many as six addressing modes are supported for each instruction.

REGISTER 3-2: CORCON: CORE CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-0
VAR	—	US1	US0	EDT(1)	DL2	DL1	DL0
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R-0	R/W-0	R/W-0
SATA	SATB	SATDW	ACCSAT	IPL3(2)	SFA	RND	IF
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **VAR:** Variable Exception Processing Latency Control bit
1 = Variable exception processing latency is enabled
0 = Fixed exception processing latency is enabled

bit 14 **Unimplemented:** Read as '0'

bit 13-12 **US<1:0>:** DSP Multiply Unsigned/Signed Control bits
11 = Reserved
10 = DSP engine multiplies are mixed-sign
01 = DSP engine multiplies are unsigned
00 = DSP engine multiplies are signed

bit 11 **EDT:** Early DO Loop Termination Control bit(1)
1 = Terminates executing the DO loop at the end of the current loop iteration
0 = No effect

bit 10-8 **DL<2:0>:** DO Loop Nesting Level Status bits
111 = 7 DO loops are active
•
•
•
001 = 1 DO loop is active
000 = 0 DO loops are active

bit 7 **SATA:** ACCA Saturation Enable bit
1 = Accumulator A saturation is enabled
0 = Accumulator A saturation is disabled

bit 6 **SATB:** ACCB Saturation Enable bit
1 = Accumulator B saturation is enabled
0 = Accumulator B saturation is disabled

bit 5 **SATDW:** Data Space Write from DSP Engine Saturation Enable bit
1 = Data Space write saturation is enabled
0 = Data Space write saturation is disabled

bit 4 **ACCSAT:** Accumulator Saturation Mode Select bit
1 = 9.31 saturation (super saturation)
0 = 1.31 saturation (normal saturation)

Note 1: This bit is always read as '0'.
2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

TABLE 4-19: NVM REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
NVMCON	0728	WR	WREN	WRERR	NVMSIDL	—	—	RPDF	URERR	—	—	—	—	NVMOP3	NVMOP2	NVMOP1	NVMOP0	0000
NVMADR	072A	NVMADR<15:0>																0000
NVMADRU	072C	—	—	—	—	—	—	—	—	NVMADRU<23:16>								0000
NVMKEY	072E	—	—	—	—	—	—	—	—	NVMKEY<7:0>								0000
NVMSRCADRL	0730	NVMSRCADR<15:1>															0	0000
NVMSRCADRH	0732	—	—	—	—	—	—	—	—	NVMSRCADR<23:16>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-20: SYSTEM CONTROL REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RCON	0740	TRAPR	IOPUWR	—	—	VREGSF	—	CM	VREGS	EXTR	SWR	SWDTEN	WDTO	SLEEP	IDLE	BOR	POR	Note 1
OSCCON	0742	—	COSC2	COSC1	COSC0	—	NOSC2	NOSC1	NOSC0	CLKLOCK	IOLOCK	LOCK	—	CF	—	—	OSWEN	Note 2
CLKDIV	0744	ROI	DOZE2	DOZE1	DOZE0	DOZEN	FRCDIV2	FRCDIV1	FRCDIV0	PLLPOST1	PLLPOST0	—	PLLPRE4	PLLPRE3	PLLPRE2	PLLPRE1	PLLPRE0	0000
PLLFBD	0746	—	—	—	—	—	—	—	PLLDIV<8:0>									0000
OSCTUN	0748	—	—	—	—	—	—	—	—	—	—	TUN<5:0>						0000

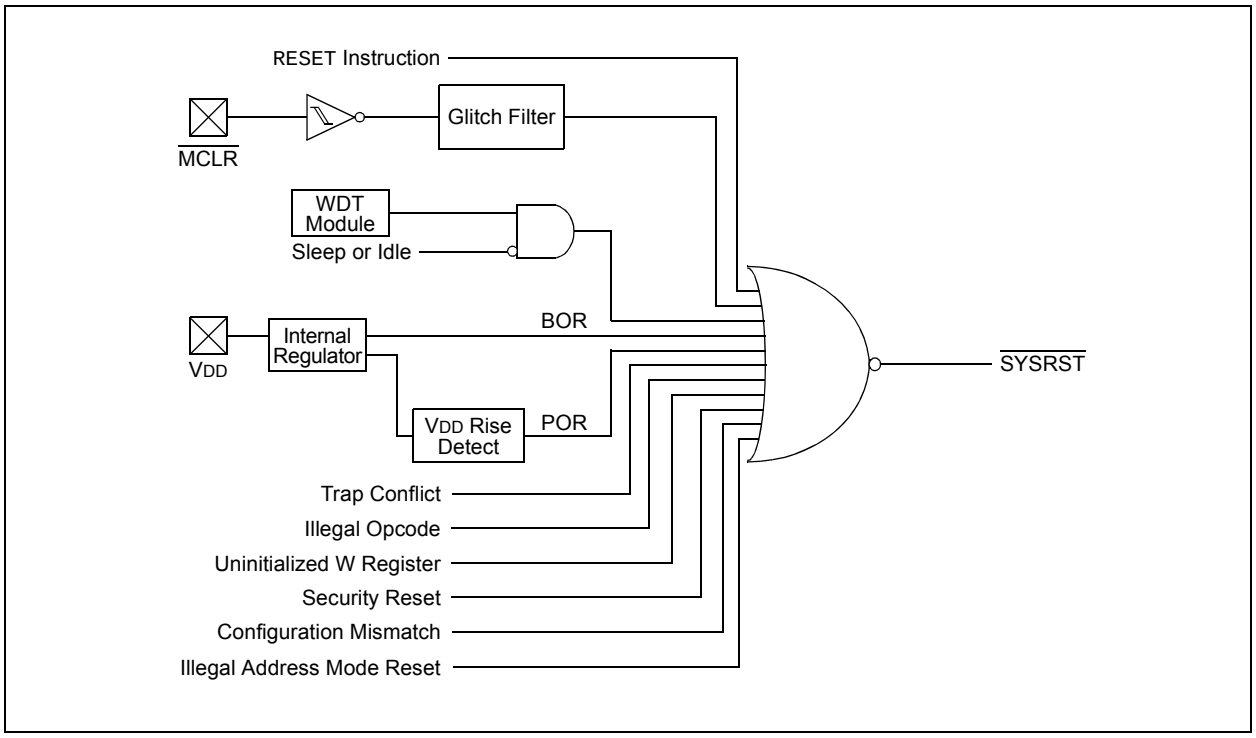
Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.
Note 1: RCON register Reset values are dependent on the type of Reset.
2: OSCCON register Reset values are dependent on the Configuration fuses.

TABLE 4-21: REFERENCE CLOCK REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
REFOCON	074E	ROON	—	ROSSLP	ROSEL	RODIV3	RODIV2	RODIV1	RODIV0	—	—	—	—	—	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

FIGURE 6-1: RESET SYSTEM BLOCK DIAGRAM



8.0 DIRECT MEMORY ACCESS (DMA)

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Direct Memory Access (DMA)"** (DS70348) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The DMA Controller transfers data between Peripheral Data registers and Data Space SRAM. For the simplified DMA block diagram, refer to Figure 8-1.

In addition, DMA can access the entire data memory space. The data memory bus arbiter is utilized when either the CPU or DMA attempts to access SRAM, resulting in potential DMA or CPU stalls.

The DMA Controller supports 4 independent channels. Each channel can be configured for transfers to or from selected peripherals. The peripherals supported by the DMA Controller include:

- CAN
- Analog-to-Digital Converter (ADC)
- Serial Peripheral Interface (SPI)
- UART
- Input Capture
- Output Compare

Refer to Table 8-1 for a complete list of supported peripherals.

FIGURE 8-1: PERIPHERAL TO DMA CONTROLLER

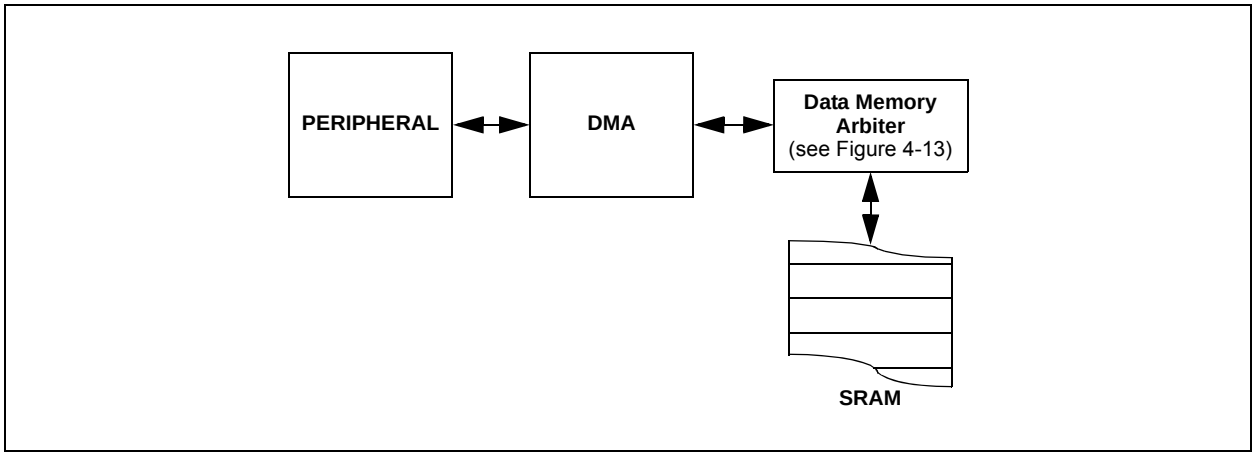
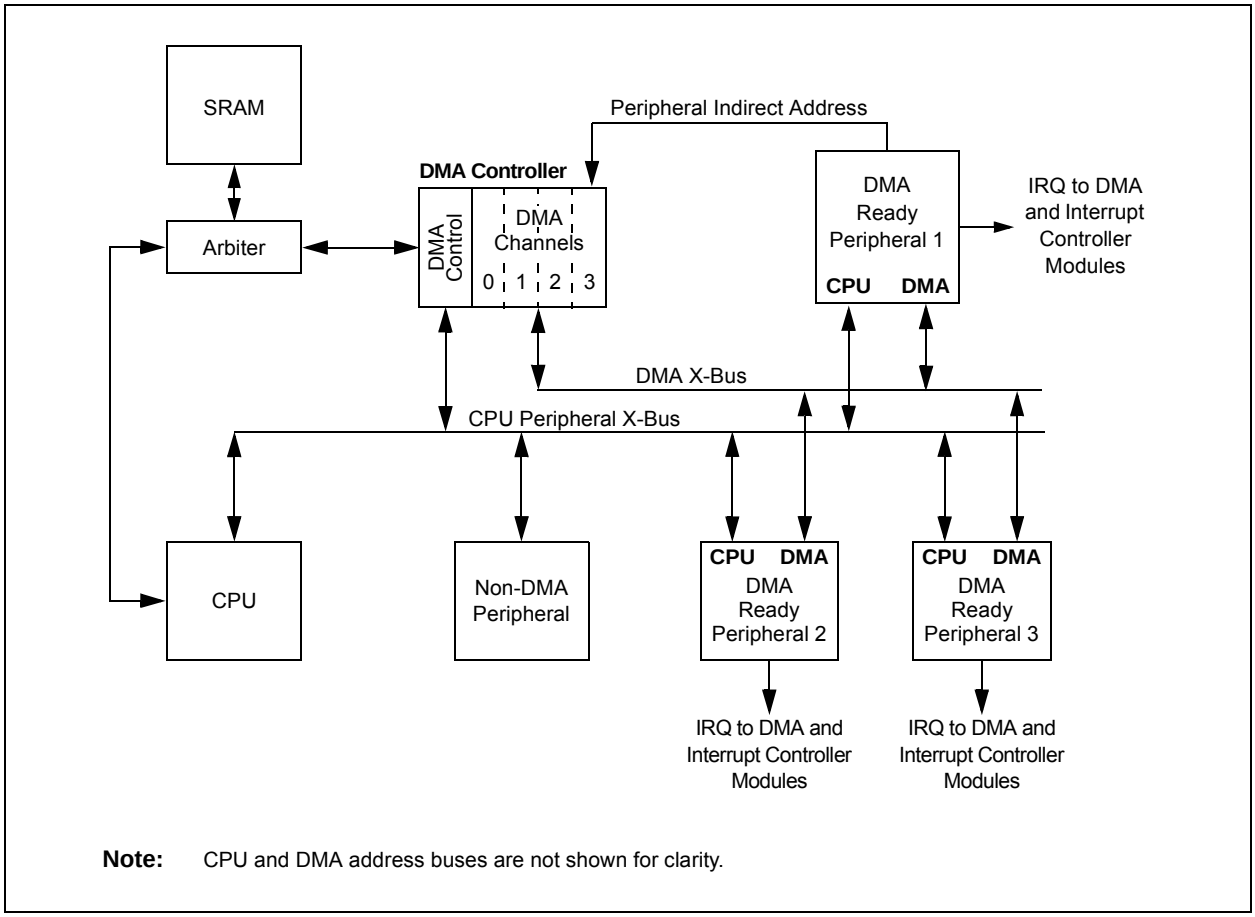


Figure 8-2 illustrates the DMA Controller block diagram.

FIGURE 8-2: DMA CONTROLLER BLOCK DIAGRAM



Note: CPU and DMA address buses are not shown for clarity.

8.1 DMAC Controller Registers

Each DMAC Channel x (where x = 0 to 3) contains the following registers:

- 16-Bit DMA Channel x Control Register (DMAxCON)
- 16-Bit DMA Channel x IRQ Select Register (DMAxREQ)
- 32-Bit DMA Channel x Start Address Register A High/Low (DMAxSTAH/L)
- 32-Bit DMA Channel x Start Address Register B High/Low (DMAxSTBH/L)
- 16-Bit DMA Channel x Peripheral Address Register (DMAxPAD)
- 14-Bit DMA Channel x Transfer Count Register (DMAxCNT)

Additional status registers (DMAPWC, DMARQC, DMAPPS, DMALCA and DSADRH/L) are common to all DMAC channels. These status registers provide information on write and request collisions, as well as on last address and channel access information.

The DMA Interrupt Flags (DMAxIF) are located in an IFSx register in the interrupt controller. The corresponding DMA Interrupt Enable bits (DMAxIE) are located in an IECx register in the interrupt controller and the corresponding DMA Interrupt Priority bits (DMAxIP) are located in an IPCx register in the interrupt controller.

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER(1,3)

U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
—	COSC2	COSC1	COSC0	—	NOSC2(2)	NOSC1(2)	NOSC0(2)
bit 15							bit 8

R/W-0	R/W-0	R-0	U-0	R/C-0	U-0	U-0	R/W-0
CLKLOCK	IOLOCK	LOCK	—	CF	—	—	OSWEN
bit 7							bit 0

Legend:	C = Clearable bit	y = Value set from Configuration bits on POR	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits (read-only)
111 = Fast RC Oscillator (FRC) with Divide-by-N
110 = Fast RC Oscillator (FRC) with Divide-by-16
101 = Low-Power RC Oscillator (LPRC)
100 = Backup FRC Oscillator (BFRC)(4)
011 = Primary Oscillator (XT, HS, EC) with PLL
010 = Primary Oscillator (XT, HS, EC)
001 = Fast RC Oscillator (FRC) Divided by N and PLL
000 = Fast RC Oscillator (FRC)

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits(2)
111 = Fast RC Oscillator (FRC) with Divide-by-N
110 = Fast RC Oscillator (FRC) with Divide-by-16
101 = Low-Power RC Oscillator (LPRC)
100 = Reserved(5)
011 = Primary Oscillator (XT, HS, EC) with PLL
010 = Primary Oscillator (XT, HS, EC)
001 = Fast RC Oscillator (FRC) Divided by N and PLL
000 = Fast RC Oscillator (FRC)

bit 7 **CLKLOCK:** Clock Lock Enable bit
1 = If FCKSM0 = 1, then clock and PLL configurations are locked; if FCKSM0 = 0, then clock and PLL configurations may be modified
0 = Clock and PLL selections are not locked, configurations may be modified

bit 6 **IOLOCK:** I/O Lock Enable bit
1 = I/O lock is active
0 = I/O lock is not active

bit 5 **LOCK:** PLL Lock Status bit (read-only)
1 = Indicates that PLL is in lock or PLL start-up timer is satisfied
0 = Indicates that PLL is out of lock, start-up timer is in progress or PLL is disabled

Note 1: Writes to this register require an unlock sequence. Refer to **"Oscillator"** (DS70580) in the *"dsPIC33/PIC24 Family Reference Manual"* (available from the Microchip web site) for details.

2: Direct clock switches between any Primary Oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transitional clock source between the two PLL modes.

3: This register resets only on a Power-on Reset (POR).

4: COSC<2:0> bits will be set to '0b100' when FRC fails.

5: User cannot write '0b100' to NOSC<2:0>. COSC<2:0> will be set to '0b100' (BFRC) when the FRC fails.

NOTES:

REGISTER 17-7: PWMCONx: PWMx CONTROL REGISTER (CONTINUED)

bit 7-6 **DTC<1:0>:** Dead-Time Control bits
11 = Dead-Time Compensation mode
10 = Dead-time function is disabled
01 = Negative dead time is actively applied for Complementary Output mode
00 = Positive dead time is actively applied for all Output modes

bit 5 **DTCP:** Dead-Time Compensation Polarity bit(3)
When Set to '1':
If DTCMPx = 0, PWMxL is shortened and PWMxH is lengthened.
If DTCMPx = 1, PWMxH is shortened and PWMxL is lengthened.
When Set to '0':
If DTCMPx = 0, PWMxH is shortened and PWMxL is lengthened.
If DTCMPx = 1, PWMxL is shortened and PWMxH is lengthened.

bit 4-3 **Unimplemented:** Read as '0'

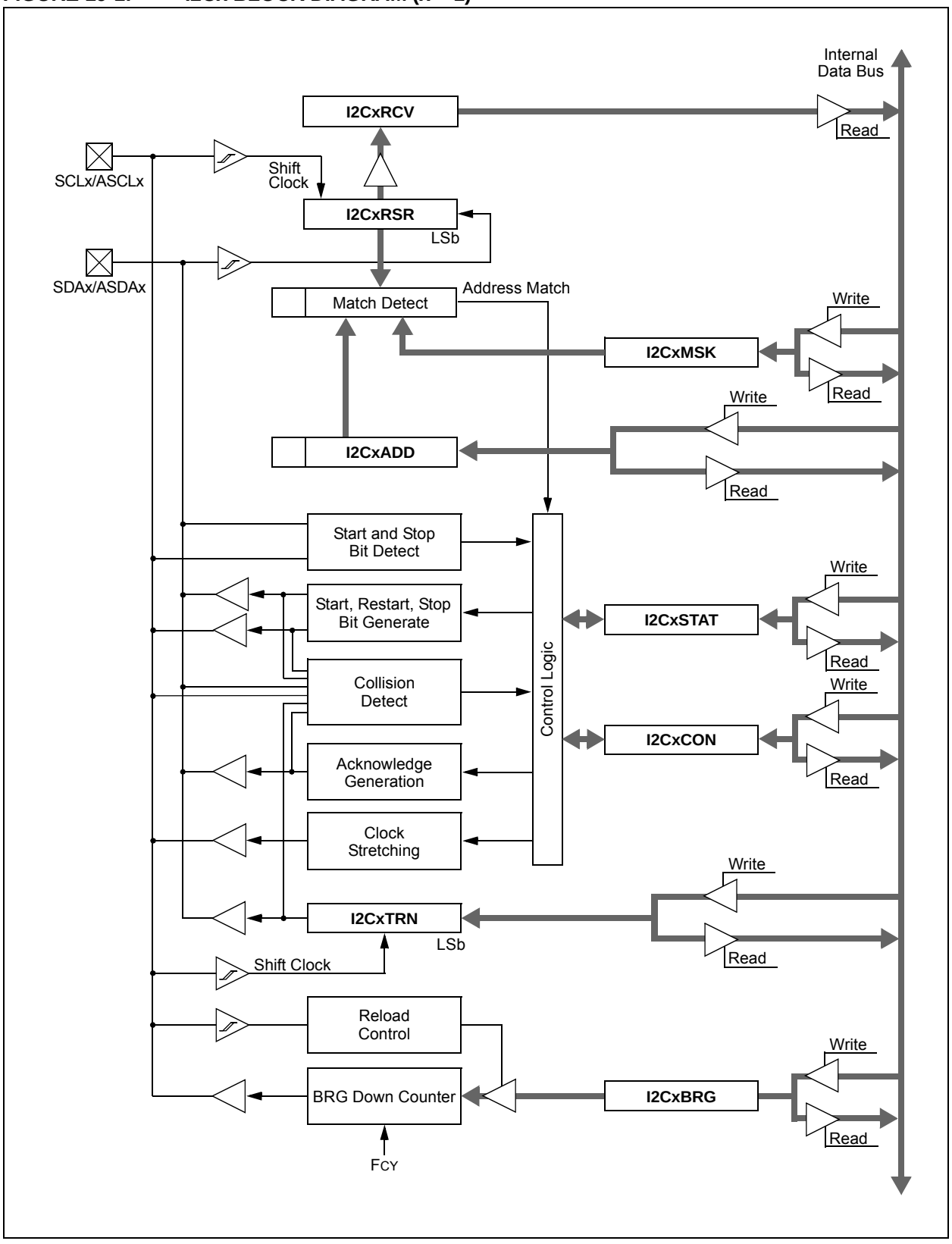
bit 2 **CAM:** Center-Aligned Mode Enable bit(2,4)
1 = Center-Aligned mode is enabled
0 = Edge-Aligned mode is enabled

bit 1 **XPRES:** External PWMx Reset Control bit(5)
1 = Current-limit source resets the time base for this PWM generator if it is in Independent Time Base mode
0 = External pins do not affect PWMx time base

bit 0 **IUE:** Immediate Update Enable bit(2)
1 = Updates to the active MDC/PDCx/DTRx/ALTDTRx/PHASEx registers are immediate
0 = Updates to the active MDC/PDCx/DTRx/ALTDTRx/PHASEx registers are synchronized to the PWMx period boundary

Note 1: Software must clear the interrupt status here and in the corresponding IFSx bit in the interrupt controller.
2: These bits should not be changed after the PWMx is enabled (PTEN = 1).
3: DTC<1:0> = 11 for DTCP to be effective; else, DTCP is ignored.
4: The Independent Time Base (ITB = 1) mode must be enabled to use Center-Aligned mode. If ITB = 0, the CAM bit is ignored.
5: To operate in External Period Reset mode, the ITB bit must be '1' and the CLMOD bit in the FCLCONx register must be '0'.

FIGURE 19-1: I2Cx BLOCK DIAGRAM (x = 1)



REGISTER 19-1: I2CxCON1: I2Cx CONTROL REGISTER 1 (CONTINUED)

bit 7 **GCEN:** General Call Enable bit (I^2C Slave mode only)
1 = Enables interrupt when a general call address is received in I2CxRSR; module is enabled for reception
0 = General call address is disabled.

bit 6 **STREN:** SCLx Clock Stretch Enable bit
In I^2C Slave mode only, used in conjunction with the SCLREL bit.
1 = Enables clock stretching
0 = Disables clock stretching

bit 5 **ACKDT:** Acknowledge Data bit
In I^2C Master mode, during Master Receive mode. The value that will be transmitted when the user initiates an Acknowledge sequence at the end of a receive.
In I^2C Slave mode when AHEN = 1 or DHEN = 1. The value that the slave will transmit when it initiates an Acknowledge sequence at the end of an address or data reception.
1 = NACK is sent
0 = ACK is sent

bit 4 **ACKEN:** Acknowledge Sequence Enable bit
In I^2C Master mode only; applicable during Master Receive mode.
1 = Initiates Acknowledge sequence on SDAx and SCLx pins, and transmits ACKDT data bit
0 = Acknowledge sequence is Idle

bit 3 **RCEN:** Receive Enable bit (I^2C Master mode only)
1 = Enables Receive mode for I^2C, automatically cleared by hardware at the end of 8-bit receive data byte
0 = Receive sequence is not in progress

bit 2 **PEN:** Stop Condition Enable bit (I^2C Master mode only)
1 = Initiates Stop condition on SDAx and SCLx pins
0 = Stop condition is Idle

bit 1 **RSEN:** Restart Condition Enable bit (I^2C Master mode only)
1 = Initiates Restart condition on SDAx and SCLx pins
0 = Restart condition is Idle

bit 0 **SEN:** Start Condition Enable bit (I^2C Master mode only)
1 = Initiates Start condition on SDAx and SCLx pins
0 = Start condition is Idle

Note 1: Automatically cleared to '0' at the beginning of slave transmission; automatically cleared to '0' at the end of slave reception.

2: Automatically cleared to '0' at the beginning of slave transmission.

REGISTER 22-13: CxBUFPNT2: CANx FILTERS 4-7 BUFFER POINTER REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F7BP3	F7BP2	F7BP1	F7BP0	F6BP3	F6BP2	F6BP1	F6BP0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F5BP3	F5BP2	F5BP1	F5BP0	F4BP3	F4BP2	F4BP1	F4BP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **F7BP<3:0>:** RX Buffer Mask for Filter 7 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F6BP<3:0>:** RX Buffer Mask for Filter 6 bits (same values as bits 15-12)

bit 7-4 **F5BP<3:0>:** RX Buffer Mask for Filter 5 bits (same values as bits 15-12)

bit 3-0 **F4BP<3:0>:** RX Buffer Mask for Filter 4 bits (same values as bits 15-12)

REGISTER 24-2: ADxCON2: ADCx CONTROL REGISTER 2 (CONTINUED)

bit 1 **BUFM:** Buffer Fill Mode Select bit
1 = Starts buffer filling the first half of the buffer on the first interrupt and the second half of the buffer on the next interrupt
0 = Always starts filling the buffer from the Start address

bit 0 **ALTS:** Alternate Input Sample Mode Select bit
1 = Uses channel input selects for Sample MUX A on the first sample and Sample MUX B on the next sample
0 = Always uses channel input selects for Sample MUX A

Note 1: The ADCx VREFH Input is connected to AVDD and the VREFL input is connected to AVSS.

31.0 HIGH-TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of the dsPIC33EVXXXGM00X/10X family electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 30.0 "Electrical Characteristics"** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter DC10 in **Section 30.0 "Electrical Characteristics"** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33EVXXXGM00X/10X family high-temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these, or any other conditions above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(2) ..... -40°C to +150°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +6.0V
Maximum current out of V_{SS} pin ..... 350 mA
Maximum current into V_{DD} pin(3) ..... 350 mA
Maximum junction temperature ..... +155°C
Maximum current sunk by any I/O pin ..... 20 mA
Maximum current sourced by I/O pin ..... 18 mA
Maximum current sunk by all ports combined ..... 200 mA
Maximum current sourced by all ports combined(3) ..... 200 mA

Note 1: Stresses above those listed under "Absolute Maximum Ratings" can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: AEC-Q100 reliability testing for devices intended to operate at +150°C is 1,000 hours. Any design in which the total operating time from +125°C to +150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

3: Maximum allowable current is a function of device maximum power dissipation (see Table 31-2).

31.1 High-Temperature DC Characteristics

TABLE 31-1: OPERATING MIPS vs. VOLTAGE

Characteristic	VDD Range (in Volts)	Temperature Range (in °C)	Max MIPS
			dsPIC33EVXXXGM00X/10X Family
HDC5	4.5V to 5.5V(1,2)	-40°C to +150°C	40

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules, such as the ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Device functionality is tested but is not characterized. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

2: When BOR is enabled, the device will work from 4.7V to 5.5V.

TABLE 31-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
High-Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+155	°C
Operating Ambient Temperature Range	TA	-40	—	+150	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD – VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 31-3: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 3): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature				
Param No.	Symbol	Characteristic	Min.	Typ.(1)	Max.	Units	Conditions
Operating Voltage							
HDC10	VDD	**Supply Voltage(3)**	VBOR	—	5.5	V	
HDC12	VDR	**RAM Data Retention Voltage(2)**	1.8	—	—	V	
HDC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	—	VSS	V	
HDC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	1.0	—	—	V/ms	0V-5.0V in 5 ms
HDC18	VCORE	**VDD Core** Internal Regulator Voltage	1.62	1.8	1.98	V	Voltage is dependent on load, temperature and VDD

Note 1: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

2: This is the limit to which VDD may be lowered without losing RAM data.

3: VDD voltage must remain at VSS for a minimum of 200 μs to ensure POR.

TABLE 31-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
Power-Down Current (IPD)						
HDC60e	1300	2500	μA	+150°C	5V	Base Power-Down Current
HDC61c	10	50	μA	+150°C	5V	Watchdog Timer Current: ΔIWDT

TABLE 31-5: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
HDC40e	2.6	5.0	mA	+150°C	5V	10 MIPS
HDC42e	3.6	7.0	mA	+150°C	5V	20 MIPS

TABLE 31-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

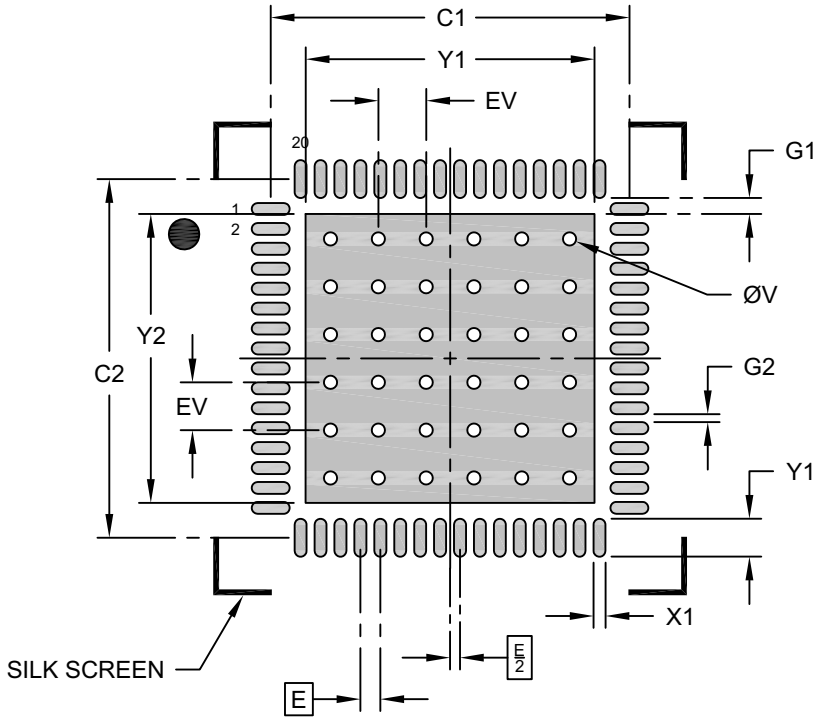
DC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
HDC20e	5.9	8.0	mA	+150°C	5V	10 MIPS
HDC22e	10.3	15.0	mA	+150°C	5V	20 MIPS
HDC23e	19.0	25.0	mA	+150°C	5V	40 MIPS

TABLE 31-7: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature				
Parameter No.	**Typical**	**Max**	**Doze Ratio**	**Units**	**Conditions**		
HDC73a	18.5	22.0	1:2	mA	+150°C	5V	40 MIPS
HDC73g	8.35	12.0	1:128	mA			

64-Lead Very Thin Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [VQFN] With 7.15 x 7.15 Exposed Pad [Also called QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2			7.25
Optional Center Pad Length	Y2			7.25
Contact Pad Spacing	C1		9.00	
Contact Pad Spacing	C2		9.00	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			0.95
Contact Pad to Center Pad (X64)	G1	0.40		
Spacing Between Contact Pads (X60)	G2	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2149C [MR]

APPENDIX A: REVISION HISTORY

Revision A (December 2013)

This is the initial version of this document.

Revision B (June 2014)

This revision incorporates the following updates:

- Sections:
  - Added **Section 31.0 “High-Temperature Electrical Characteristics”**
  - Updated the **“Power Management”**section, the **“Input/Output”** section, **Section 3.3 “Data Space Addressing”**, **Section 4.2 “Data Address Space”**, **Section 4.3.2 “Extended X Data Space”**, **Section 4.6.1 “Bit-Reversed Addressing Implementation”**, **Section 7.4.1 “INTCON1 through INTCON4”**, **Section 11.7 “I/O Helpful Tips”**
  - Updated note in **Section 17.0 “High-Speed PWM Module”**, **Section 18.0 “Serial Peripheral Interface (SPI)”**, **Section 27.8 “Code Protection and CodeGuard™ Security”**
  - Updated title of **Section 20.0 “Single-Edge Nibble Transmission (SENT)”**
  - Updated **Section 34.0 “Packaging Information”**. Deleted e3, Pb-free and Industrial (I) temperature range indication throughout the section, and updated the packaging diagrams
  - Updated the **“Product Identification System”** section
- Registers:
  - Updated Register 3-2, Register 7-2, Register 7-6, Register 9-2, Register 11-3, Register 14-1, Register 14-3, Register 14-11, Register 15-1, Register 22-4
- Figures:
  - Added Figure 4-6, Figure 4-8, Figure 4-14, Figure 4-15, Figure 14-1, Figure 16-1, Figure 17-2, Figure 23-1, Figure 24-1
- Tables:
  - Updated Table 1, Table 27-1, Table 27-2, Table 30-6, Table 30-7, Table 30-8, Table 30-9, Table 30-10, Table 30-11, Table 30-12, Table 30-38, Table 30-50, Table 30-53 and added Table 31-11,
- Changes to text and formatting were incorporated throughout the document

Revision C (November 2014)

This revision incorporates the following updates:

- Sections:
  - Added note in **Section 5.2 “RTSP Operation”**
  - Updated “**Section 5.4 “Error Correcting Code (ECC)”**
  - Deleted 44-Terminal Very Thin Leadless Array Package (TL) - 6x6x0.9 mm Body With Exposed Pad (VTLA).
- Registers
  - Updated Register 7-6
- Figures:
  - Updated Figure 4-1, Figure 4-3, Figure 4-4
- Tables:
  - Updated Table 27-2, Table 31-13, Table 31-14, Table 31-15
  - Added Table 31-16, Table 31-17

Revision D (April 2015)

This revision incorporates the following updates:

- Sections:
  - Updated the Clock Management, Timers/ Output Compare/Input Capture, Communication Interfaces and Input/Output sections at the beginning of the data sheet (Page 1 and Page 2).
  - Updated all pin diagrams at the beginning of the data sheet (Page 4 through Page 9).
  - Added **Section 11.6 “High-Voltage Detect (HVD)”**
  - Updated **Section 13.0 “Timer2/3 and Timer4/5”**
  - Corrects all Buffer heading numbers in **Section 22.4 “CAN Message Buffers”**
- Registers
  - Updated Register 3-2, Register 25-2, Register 26-2
- Figures
  - Updated Figure 26-1, Figure 30-5, Figure 30-32
- Tables
  - Updated Table 1, Table 4-25, Table 30-10, Table 30-22, Table 30-53 and Table 31-8
- Changes to text and formatting were incorporated throughout the document